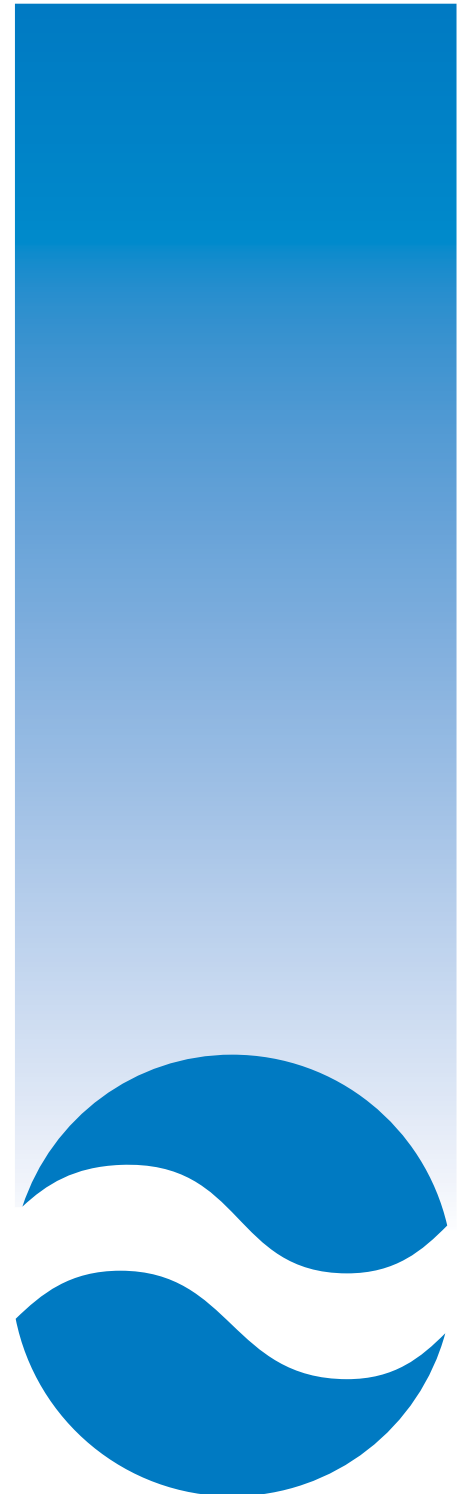


IPC J-STD-001GS-AM1
Amendment 1
January 2020

JOINT INDUSTRY STANDARD

Space and Military
Applications Electronic
Hardware Addendum to
IPC J-STD-001G
Requirements for
Soldered Electrical
and Electronic
Assemblies

Amendment 1



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Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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IPC J-STD-001GS-AM1

Space and Military Applications Electronic Hardware Addendum to IPC J-STD-001G Requirements for Soldered Electrical and Electronic Assemblies Amendment 1

Developed by the J-STD-001 Space and Military Electronic Assemblies Task Group (5-22as) of the Assembly & Joining Committee (5-20) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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